

AMENDMENT AND RESPONSE**PAGE 2**

Serial No.: 10/073,701

Filing Date: 2/11/2002

Attorney Docket No. 100.365US01

Title: ELECTRICAL CONNECTIONS WITHIN SUBSTRATES

Amendments to the Specification:

Please change the Title of the application to: "Method for Transmitting Current through a Substrate."

Please delete the Abstract currently on file, and replace it with the following:

"A method for transmitting high-frequency current through a substrate is provided. The method comprises receiving the high-frequency current at a via passing through at least one conductive plane disposed within the substrate and coupled to the via with one or more tabs which span a gap between the at least one conductive plane and the via; and directing the high-frequency current along an uninterrupted path substantially on a surface of the via thereby bypassing the at least one conductive plane by conducting at least a portion of the high-frequency current between the one or more tabs."